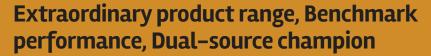
# BERGSTAK® 0.8MM MEZZANINE CONNECTORS





# FLEXIBLE SOLUTION FOR HIGH DENSITY APPLICATIONS

FCI's BergStak® 0.8mm is a flexible solution designed for high speed and high density, parallel board-to-board connector system with 16 PCB stack heights in 9 sizes up to 200 positions.

- Housing and terminal profile guarantees support of up to 12Gb/s
- Vertical versus vertical mating configuration
- 40 to 200 position sizes in 20 position increments
- 5mm to 20mm stack heights in 1mm increments



#### **FEATURES**

- Housing and terminal profile guarantees support of up to 12Gb/s
- Vertical versus vertical mating configuration
- 40 to 200 position sizes in 20 position increments
- 5mm to 20mm stack heights in 1mm increments
- 0.8mm double-row contact pitch conserves printed circuit board space
- Scoop-proof feature housings
- Multiple plating options available
- Multiple packaging options available
- PCB locator pegs option
- Available in UL94-V0 material
- RoHS compliant and lead-free

#### **BENEFITS**

- Compatible with PCIe Gen 2/3 and SAS 3.0 high speed performance on selected stack heights
- Suitable for parallel board stacking applications
- Comprehensive range of sizes and stack heights to satisfy all needs
- High density for all electrical applications needs
- Prevents reverse mating
- Satisfies different application requirement
- Suitable for varies feeding processing
- Facilitates ease and accuracy during manual assembly
- · High flammability rating
- Meets environmental, health and safety requirements

The PCIe® mark is a registered trademark of the PCI-SIG Corp

## TECHNICAL INFORMATION

#### **MATERIAL**

- Housing: Glass filled LCP, UL94V-0
- Contact Base Metal
  - Receptacle: Copper Alloy, High Spring
- Plug: Brass
- Contact Area Finish: Gold or Gold flash over Palladium-nickel (GXT) over Nickel
- Solder Area Finish: Matte pure Tin over Nickel

#### **MECHANICAL PERFORMANCE**

- Durability: 100 mating cycles
- Mating Force: 0.9N max./contact
- Unmating Force: 0.1N min./contact

#### **ELECTRICAL PERFORMANCE**

- Insulation Resistance:
  - Initial:  $1000M\Omega$  min.
  - After Test: 100MΩ min.
- Current Rating: 0.8A/contact
- Contact Resistance:
  - Initial:  $30m\Omega$  max.
  - After Test: 50mΩ max.
- Voltage Rating: 100VAC
- Signal Integrity (Differential pairs, connector and SMT pads only)
  - Impedance Range: 81 to  $108\Omega$  @ 50 ps edge (10–90%)
  - Return Loss: < 10dB up to 5GHz
  - Insertion Loss: < 1.5dB up to 5GHz</p>
  - $\blacksquare$  NEXT:  $\leq$  4.0% for a 50 ps edge (10-90%)
  - FEXT:  $\leq$  2.4% for a 50 ps edge (10-90%)

#### **ENVIRONMENTAL**

- Temperature Range: -40°C to +125°C
- High Temperature Life: 105°C ± 5°C for 1000 hours
- Humidity: 90-95% relative humidity for 96 hours
- Mixed Flowing Gas Class 2a (30 GXT)

#### **APPROVALS AND CERTIFICATIONS**

- UL E66906
- File no. LR46923

#### **SPECIFICATIONS**

- Product Specification: GS-12-547
- Test Report: DGS-29-010

#### **PACKAGING**

- Tape & Reel
- Tubes

#### **TARGET MARKETS/APPLICATIONS**



Router IP Phone



Server



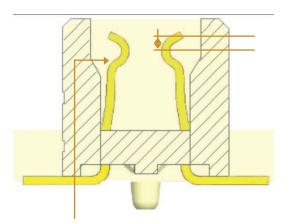
Industrial and Instrumentation
Office Equipment
Test and Measurement
Point-Of-Sale Terminal
Portable Industrial Terminal



**Diagnostics System** 

### **▶** BERGSTAK® 0.8MM MEZZANINE CONNECTORS

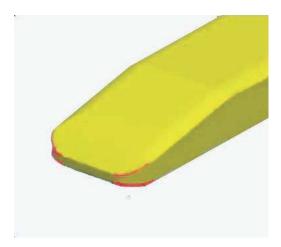
# **RECEPTACLE**



Early-contact point allows early engagement/ late disengagement and increases mating wipe

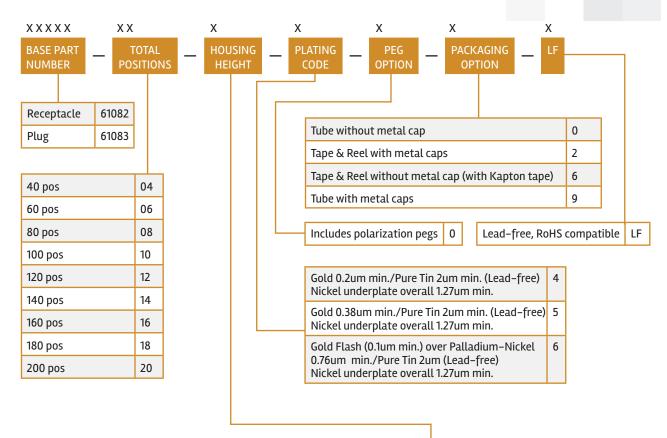
Precision-tapered contacts control mating stress while providing reliable, high normal force

# **HEADER**



Coined contact tips assure smooth, safe wiping action during connector mating

# **PART NUMBER SELECTOR**



X	FOR PLUG, SEE DWG. NO. 61083				
COMBINATION	Plug 1	Plug 2	Plug 3	Plug 4 Prof	
OF  MATED HEIGHT	l ma		[6.]	]  [2]	
Recep 1					
m <del>dt</del>	digital 1	d <u>la et 1</u>	dig	4	
Recep 2	TERET T	<b>199</b>			
		TRIÊTET T	[ND_00]	<u> </u>	
Recep 3	raffer -	<b>शिय</b> ।			
				<b>1</b>	
7:1					
Recep 4	<u> </u>	<u> </u>	<u> </u>		
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